IPC ASSOCIATION CON ELECTRONICS IND	Material Comp © Copyright 2005. International and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
upplier In	formation						<u> </u>								
Company nam	ne*	Company unique ID			J	Unique ID Authority				Respon	Response Date*				
nsemi										2023-06	2023-06-12				
Contact Name	:	Title - Contact			I	Phone - Contact*				Email -	Email - Contact*				
Product-Env-	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-	Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Red	quester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Versi	on :	Manufacturing Site		Weight*	UOM	Unit Type	
		LC05111C02MTTTG 1 cell LiB Protect		1 cell LiB Protection	on IC		2023-06-12 PHM		PHM	24.0		mg	Each		
Ianufactur	ring Proccess Informa	ntion						•					·		
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperat		y Temperatu	ture Max Time at Peak Tempera		ture Numb	per of Reflow Cyc	eles		
contains Bi		CU Alloy 3			260 C		C	30	secor	nds 3					
omments															
TTENTION:	: MSL 3 Rated item require	es Bake and D	ry Pack (after	electrical test)											
or more infor	rmation regarding material	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.4	mg	Supplier	Silicon (Si)	7440-21-3		2.4	mg
Die Attach	0.74	mg	Supplier	Silver (Ag)	7440-22-4		0.0177	mg
			A	Lead (Pb)	7439-92-1	7a	0.6545	mg
			Supplier	Epoxy resins	129915-35-1		0.0243	mg
			Supplier	Tin (Sn)	7440-31-5		0.0354	mg
			Supplier	Acrylic resins	Proprietary Data		0.0081	mg
Lead Frame	8.89	mg	Supplier	Tin (Sn)	7440-31-5		0.0133	mg
			Supplier	Copper (Cu)	7440-50-8		8.8767	mg
Mold Compound-Black	9.6	mg		Epoxy Phenol Resin	proprietary data		0.0768	mg
			Supplier	Carbon Black (C)	1333-86-4		0.096	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.576	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.68	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.152	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0192	mg
Plating	2.2	mg	В	Bismuth (Bi)	7440-69-9		0.0132	mg
			Supplier	Tin (Sn)	7440-31-5		2.1868	mg
Wire Bond - Au	0.17	mg	Supplier	Gold (Au)	7440-57-5		0.17	mg